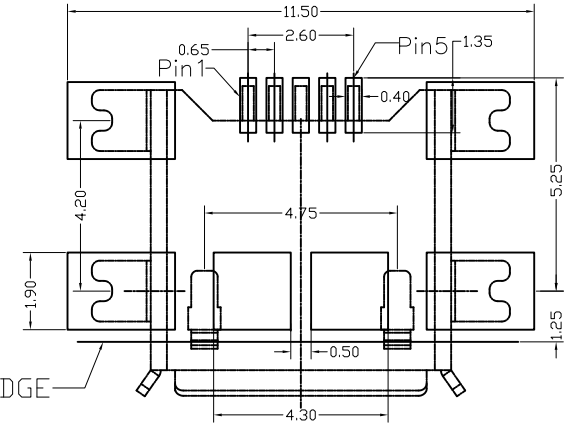
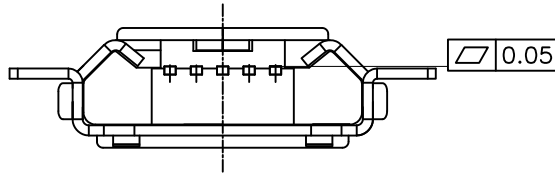


修改序号	修改说明	签名	日期
A/0			



RECOMMENDED PCB LAYOUT

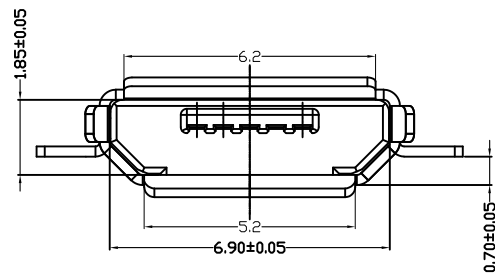
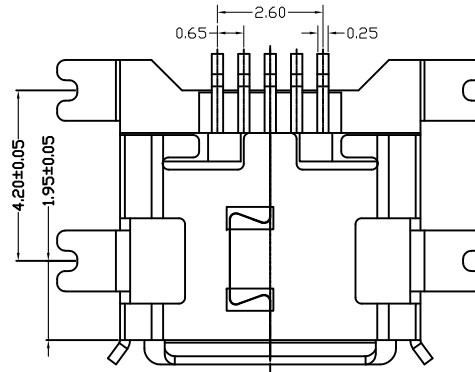
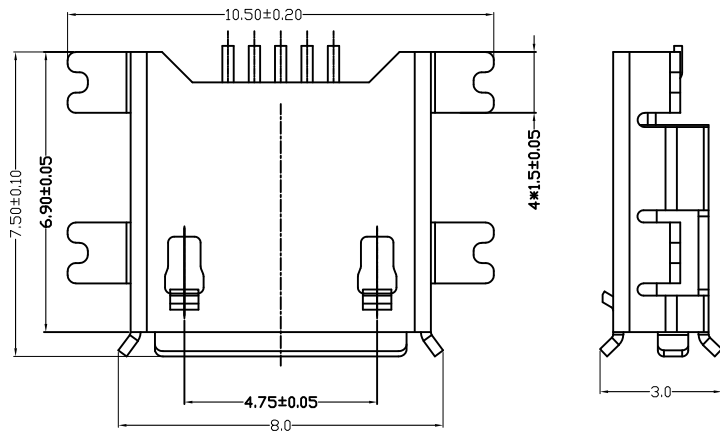
Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy,  $t=0.20\text{mm}$
- 1.3 Shell: C2680R-H or SUS,  $t=0.25\text{mm}$

2. Specification:

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100V (AC) for 1 min.
- 2.3 Contact resistance:  $40\text{m}\Omega$  Max.
- 2.4 Insulation resistance:  $100\text{M}\Omega$  min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf  
Min. 0.81~2.05 Kgf Min.  
after 3000 or 10,000 insertion/  
extration cycles
- 2.7 Temperature range:  $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$



尺寸	允许公差
.X	±0.50
.X	±0.20
.XX	±0.10
.XXX	±0.03
角度	±1.00°

深圳市创勤科技有限公司  
Shenzhen Chuangqin Technology Co., Ltd.

图纸类型		图纸名称:	
产品工程图		MICRO USB 5P BF四脚SMT沉板0.7	
设计	LIN YUN	2011.05.22	产品料号
审核			CQ28-MFCB05133016
		视图	版号: A/0

